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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

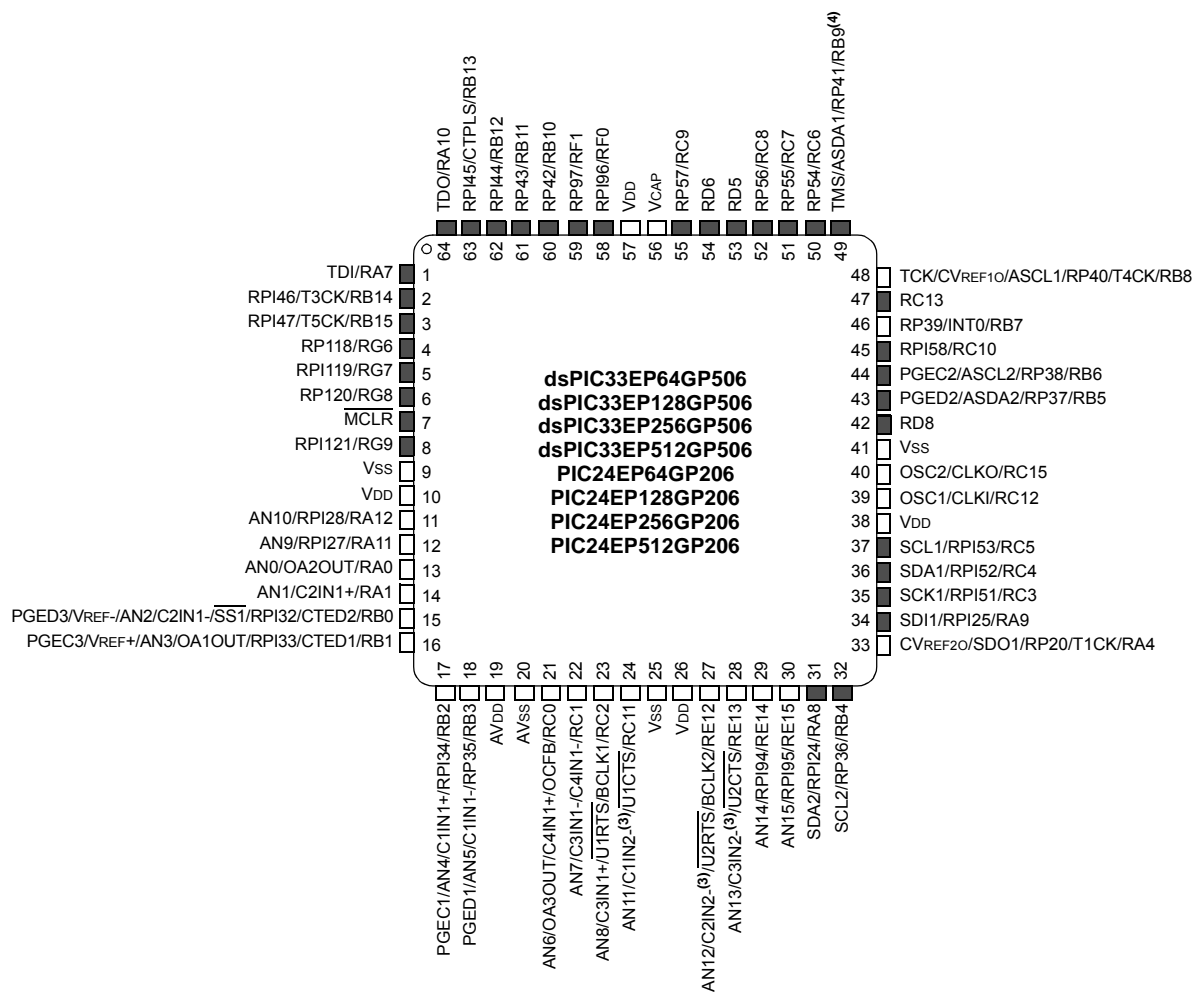
#### Details

Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPS
Connectivity	I <sup>2</sup> C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic24ep128mc202-h-mm">https://www.e-xfl.com/product-detail/microchip-technology/pic24ep128mc202-h-mm</a>

## Pin Diagrams (Continued)

64-Pin TQFP<sup>(1,2,3)</sup>

■ = Pins are up to 5V tolerant

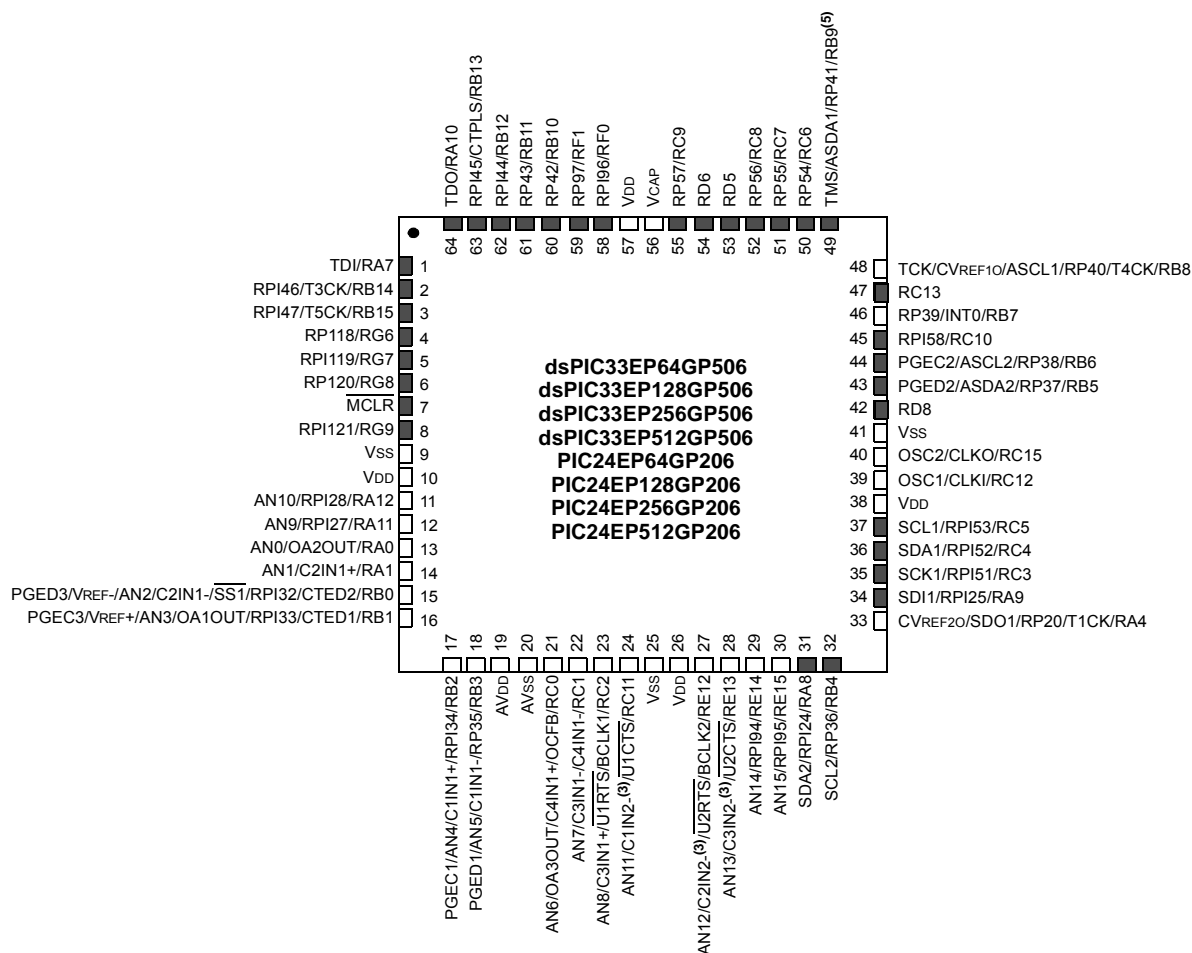


- Note**
- 1: The RPN/RPI pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.
  - 2: Every I/O port pin (RAX-RGx) can be used as a Change Notification pin (CNAX-CNGx). See **Section 11.0 “I/O Ports”** for more information.
  - 3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to Vss externally.
  - 4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

## Pin Diagrams (Continued)

64-Pin QFN<sup>(1,2,3,4)</sup>

■ = Pins are up to 5V tolerant



- Note 1:** The RPN/RPIN pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.
- Note 2:** Every I/O port pin (RAX-RGX) can be used as a Change Notification pin (CNAX-CNGX). See **Section 11.0 “I/O Ports”** for more information.
- Note 3:** This pin is not available as an input when OPMODE (CMxCON<10>) = 1.
- Note 4:** The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to Vss externally.
- Note 5:** There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

**TABLE 4-2: CPU CORE REGISTER MAP FOR PIC24EPXXXGP/MC20X DEVICES ONLY**

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets	
W0	0000	W0 (WREG)																xxxx	
W1	0002	W1																xxxx	
W2	0004	W2																xxxx	
W3	0006	W3																xxxx	
W4	0008	W4																xxxx	
W5	000A	W5																xxxx	
W6	000C	W6																xxxx	
W7	000E	W7																xxxx	
W8	0010	W8																xxxx	
W9	0012	W9																xxxx	
W10	0014	W10																xxxx	
W11	0016	W11																xxxx	
W12	0018	W12																xxxx	
W13	001A	W13																xxxx	
W14	001C	W14																xxxx	
W15	001E	W15																xxxx	
SPLIM	0020	SPLIM<15:0>																0000	
PCL	002E	PCL<15:1>																—	0000
PCH	0030	—	—	—	—	—	—	—	—	—	PCH<6:0>							0000	
DSRPAG	0032	—	—	—	—	—	—	DSRPAG<9:0>										0001	
DSWPAG	0034	—	—	—	—	—	—	—	DSWPAG<8:0>										0001
RCOUNT	0036	RCOUNT<15:0>																0000	
SR	0042	—	—	—	—	—	—	—	DC	IPL2	IPL1	IPL0	RA	N	OV	Z	C	0000	
CORCON	0044	VAR	—	—	—	—	—	—	—	—	—	—	—	IPL3	SFA	—	—	0020	
DISICNT	0052	—	—	DISICNT<13:0>														0000	
TBLPAG	0054	—	—	—	—	—	—	—	—	TBLPAG<7:0>									0000
MSTRPR	0058	MSTRPR<15:0>																0000	

**Legend:** x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

**TABLE 4-45: DMAC REGISTER MAP**

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets	
DMA0CON	0B00	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000	
DMA0REQ	0B02	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>									00FF
DMA0STAL	0B04	STA<15:0>																	0000
DMA0STAH	0B06	—	—	—	—	—	—	—	—	STA<23:16>									0000
DMA0STBL	0B08	STB<15:0>																	0000
DMA0STBH	0B0A	—	—	—	—	—	—	—	—	STB<23:16>									0000
DMA0PAD	0B0C	PAD<15:0>																	0000
DMA0CNT	0B0E	—	—	CNT<13:0>														0000	
DMA1CON	0B10	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000	
DMA1REQ	0B12	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>									00FF
DMA1STAL	0B14	STA<15:0>																	0000
DMA1STAH	0B16	—	—	—	—	—	—	—	—	STA<23:16>									0000
DMA1STBL	0B18	STB<15:0>																	0000
DMA1STBH	0B1A	—	—	—	—	—	—	—	—	STB<23:16>									0000
DMA1PAD	0B1C	PAD<15:0>																	0000
DMA1CNT	0B1E	—	—	CNT<13:0>														0000	
DMA2CON	0B20	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000	
DMA2REQ	0B22	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>									00FF
DMA2STAL	0B24	STA<15:0>																	0000
DMA2STAH	0B26	—	—	—	—	—	—	—	—	STA<23:16>									0000
DMA2STBL	0B28	STB<15:0>																	0000
DMA2STBH	0B2A	—	—	—	—	—	—	—	—	STB<23:16>									0000
DMA2PAD	0B2C	PAD<15:0>																	0000
DMA2CNT	0B2E	—	—	CNT<13:0>														0000	
DMA3CON	0B30	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000	
DMA3REQ	0B32	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>									00FF
DMA3STAL	0B34	STA<15:0>																	0000
DMA3STAH	0B36	—	—	—	—	—	—	—	—	STA<23:16>									0000
DMA3STBL	0B38	STB<15:0>																	0000
DMA3STBH	0B3A	—	—	—	—	—	—	—	—	STB<23:16>									0000
DMA3PAD	0B3C	PAD<15:0>																	0000
DMA3CNT	0B3E	—	—	CNT<13:0>														0000	
DMA3PWC	0BF0	—	—	—	—	—	—	—	—	—	—	—	—	PWCOL3	PWCOL2	PWCOL1	PWCOL0	0000	
DMA3RQC	0BF2	—	—	—	—	—	—	—	—	—	—	—	—	RQCOL3	RQCOL2	RQCOL1	RQCOL0	0000	
DMA3PPS	0BF4	—	—	—	—	—	—	—	—	—	—	—	—	PPST3	PPST2	PPST1	PPST0	0000	
DMA3LCA	0BF6	—	—	—	—	—	—	—	—	—	—	—	—	LSTCH<3:0>				000F	
DSADRL	0BF8	DSADR<15:0>																	0000
DSADRH	0BFA	—	—	—	—	—	—	—	—	DSADR<23:16>									0000

**Legend:** — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

#### 4.8.1 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The TBLRDH and TBLWTH instructions offer a direct method of reading or writing the lower word of any address within the Program Space without going through Data Space. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a Program Space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to Data Space addresses. Program memory can thus be regarded as two 16-bit-wide word address spaces, residing side by side, each with the same address range. TBLRDH and TBLWTH access the space that contains the least significant data word. TBLRDH and TBLWTH access the space that contains the upper data byte.

Two table instructions are provided to move byte or word-sized (16-bit) data to and from Program Space. Both function as either byte or word operations.

- TBLRDH (Table Read High):
  - In Word mode, this instruction maps the lower word of the Program Space location ( $P<15:0>$ ) to a data address ( $D<15:0>$ )

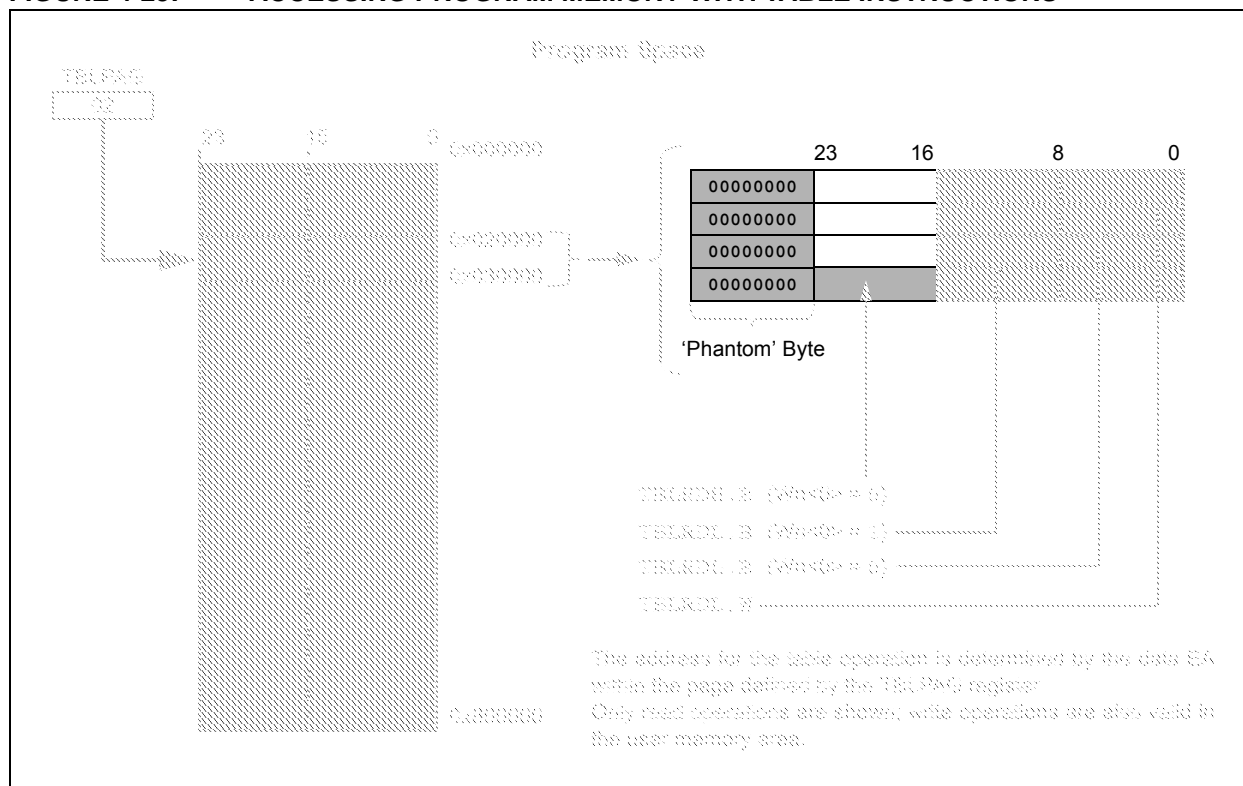
- In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when Byte Select is '1'; the lower byte is selected when it is '0'.

- TBLRDH (Table Read High):
  - In Word mode, this instruction maps the entire upper word of a program address ( $P<23:16>$ ) to a data address. The 'phantom' byte ( $D<15:8>$ ) is always '0'.
  - In Byte mode, this instruction maps the upper or lower byte of the program word to  $D<7:0>$  of the data address in the TBLRDH instruction. The data is always '0' when the upper 'phantom' byte is selected (Byte Select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a Program Space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user application and configuration spaces. When  $TBLPAG<7> = 0$ , the table page is located in the user memory space. When  $TBLPAG<7> = 1$ , the page is located in configuration space.

**FIGURE 4-23: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS**



**REGISTER 9-4: OSCTUN: FRC OSCILLATOR TUNING REGISTER**

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TUN5	TUN4	TUN3	TUN2	TUN1	TUN0
bit 7							bit 0

**Legend:**

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-6

**Unimplemented:** Read as '0'

bit 5-0

**TUN<5:0>:** FRC Oscillator Tuning bits

011111 = Maximum frequency deviation of 1.453% (7.477 MHz)

011110 = Center frequency + 1.406% (7.474 MHz)

• • •

000001 = Center frequency + 0.047% (7.373 MHz)

000000 = Center frequency (7.37 MHz nominal)

111111 = Center frequency – 0.047% (7.367 MHz)

• • •

100001 = Center frequency – 1.453% (7.263 MHz)

100000 = Minimum frequency deviation of -1.5% (7.259 MHz)

### 11.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx and TRISx registers for data control, port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs other than VDD by using external pull-up resistors. The maximum open-drain voltage allowed on any pin is the same as the maximum VIH specification for that particular pin.

See the “Pin Diagrams” section for the available 5V tolerant pins and Table 30-11 for the maximum VIH specification for each pin.

## 11.2 Configuring Analog and Digital Port Pins

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs or outputs must have their corresponding ANSELx and TRISx bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

Pins with analog functions affected by the ANSELx registers are listed with a buffer type of analog in the Pinout I/O Descriptions (see Table 1-1).

If the TRISx bit is cleared (output) while the ANSELx bit is set, the digital output level (VOH or VOL) is converted by an analog peripheral, such as the ADC module or comparator module.

When the PORTx register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

### 11.2.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a NOP, as shown in Example 11-1.

## 11.3 Input Change Notification (ICN)

The Input Change Notification function of the I/O ports allows devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature can detect input Change-of-States even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a Change-of-State.

Three control registers are associated with the Change Notification (CN) functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each I/O pin also has a weak pull-up and a weak pull-down connected to it. The pull-ups and pull-downs act as a current source or sink source connected to the pin and eliminate the need for external resistors when push button, or keypad devices are connected. The pull-ups and pull-downs are enabled separately, using the CNPUs and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

**Note:** Pull-ups and pull-downs on Change Notification pins should always be disabled when the port pin is configured as a digital output.

### EXAMPLE 11-1: PORT WRITE/READ EXAMPLE

```
MOV    0xFF00, W0    ; Configure PORTB<15:8>
                        ; as inputs
MOV    W0, TRISB      ; and PORTB<7:0>
                        ; as outputs
NOP                                ; Delay 1 cycle
BTSS   PORTB, #13     ; Next Instruction
```



TABLE 11-2: INPUT PIN SELECTION FOR SELECTABLE INPUT SOURCES (CONTINUED)

Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment	Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment
010 1000	I/O	RP40	101 0101	—	—
010 1001	I/O	RP41	101 0110	—	—
010 1010	I/O	RP42	101 0111	—	—
010 1011	I/O	RP43	101 1000	—	—
010 1100	I	RPI44	101 1001	—	—
101 1010	—	—	110 1101	—	—
101 1011	—	—	110 1110	—	—
101 1100	—	—	110 1111	—	—
101 1101	—	—	111 0000	—	—
101 1110	I	RPI94	111 0001	—	—
101 1111	I	RPI95	111 0010	—	—
110 0000	I	RPI96	111 0011	—	—
110 0001	I/O	RP97	111 0100	—	—
110 0010	—	—	111 0101	—	—
110 0011	—	—	111 0110	I/O	RP118
110 0100	—	—	111 0111	I	RPI119
110 0101	—	—	111 1000	I/O	RP120
110 0110	—	—	111 1001	I	RPI121
110 0111	—	—	111 1010	—	—
110 1000	—	—	111 1011	—	—
110 1001	—	—	111 1100	—	—
110 1010	—	—	111 1101	—	—
110 1011	—	—	111 1110	—	—
110 1100	—	—	111 1111	—	—

**Legend:** Shaded rows indicate PPS Input register values that are unimplemented.

**Note 1:** See Section 11.4.4.1 “Virtual Connections” for more information on selecting this pin assignment.

**2:** These inputs are available on dsPIC33EPXXXGP/MC50X devices only.

## 11.5 I/O Helpful Tips

1. In some cases, certain pins, as defined in Table 30-11, under “Injection Current”, have internal protection diodes to VDD and VSS. The term, “Injection Current”, is also referred to as “Clamp Current”. On designated pins, with sufficient external current-limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings, with respect to the VSS and VDD supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes, that the resulting current being injected into the device, that is clamped internally by the VDD and VSS power rails, may affect the ADC accuracy by four to six counts.
2. I/O pins that are shared with any analog input pin (i.e., ANx) are always analog pins by default after any Reset. Consequently, configuring a pin as an analog input pin automatically disables the digital input pin buffer and any attempt to read the digital input level by reading PORTx or LATx will always return a ‘0’, regardless of the digital logic level on the pin. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the Analog Pin Configuration registers in the I/O ports module (i.e., ANSELx) by setting the appropriate bit that corresponds to that I/O port pin to a ‘0’.

**Note:** Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0x0, while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.

3. Most I/O pins have multiple functions. Referring to the device pin diagrams in this data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name from left-to-right. The left most function name takes precedence over any function to its right in the naming convention. For example: AN16/T2CK/T7CK/RC1. This indicates that AN16 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.
4. Each pin has an internal weak pull-up resistor and pull-down resistor that can be configured using the CNPUs and CNPDx registers, respectively. These resistors eliminate the need for external resistors in certain applications. The internal pull-up is up to  $\sim(VDD - 0.8)$ , not VDD. This value is still above the minimum VIH of CMOS and TTL devices.

5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the VOH/IOH and VOL/IOL DC characteristic specification. The respective IOH and IOL current rating only applies to maintaining the corresponding output at or above the VOH, and at or below the VOL levels. However, for LEDs, unlike digital inputs of an externally connected device, they are not governed by the same minimum VIH/VIL levels. An I/O pin output can safely sink or source any current less than that listed in the absolute maximum rating section of this data sheet. For example:

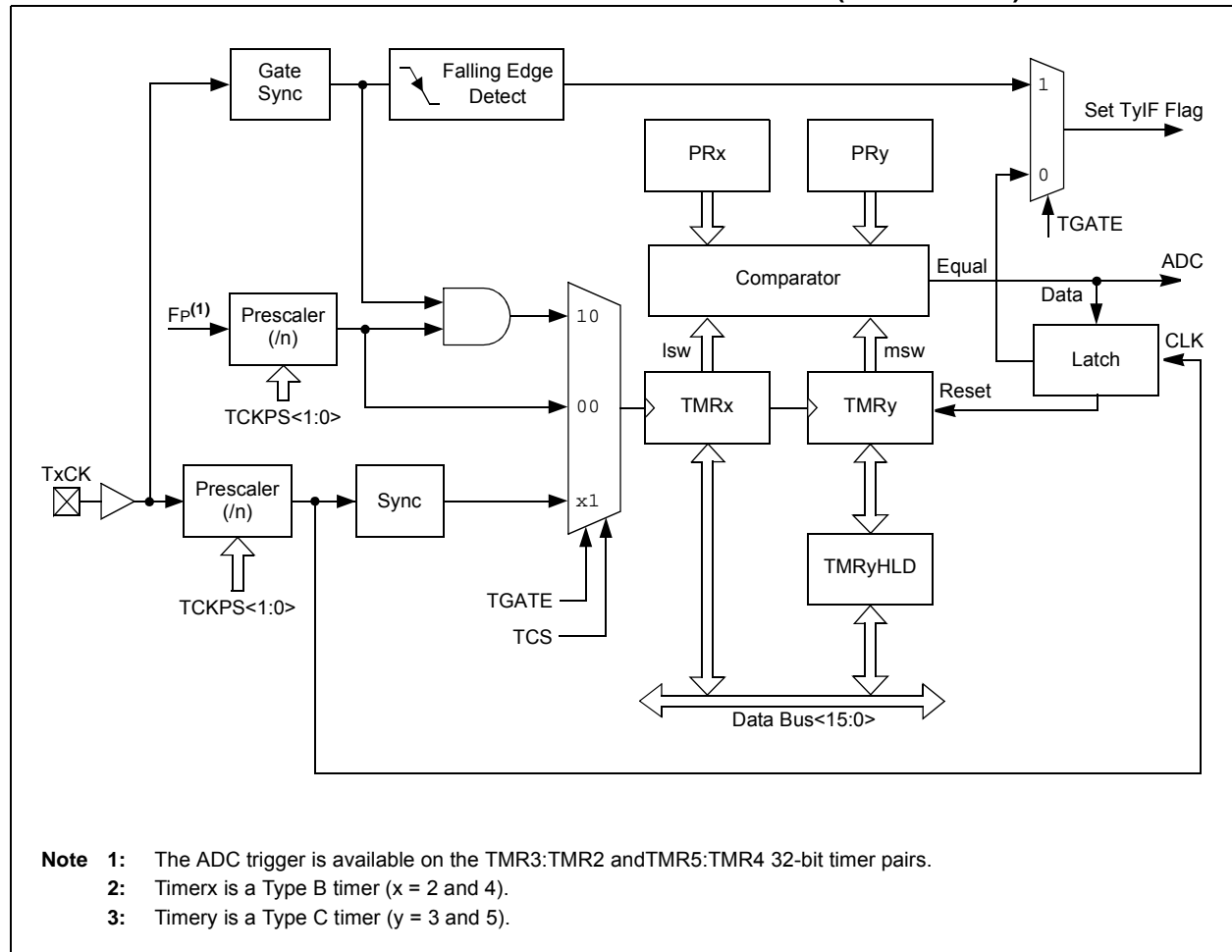
$$VOH = 2.4V @ IOH = -8 \text{ mA and } VDD = 3.3V$$

The maximum output current sourced by any 8 mA I/O pin = 12 mA.

LED source current < 12 mA is technically permitted. Refer to the VOH/IOH graphs in **Section 30.0 “Electrical Characteristics”** for additional information.

6. The Peripheral Pin Select (PPS) pin mapping rules are as follows:
  - a) Only one “output” function can be active on a given pin at any time, regardless if it is a dedicated or remappable function (one pin, one output).
  - b) It is possible to assign a “remappable output” function to multiple pins and externally short or tie them together for increased current drive.
  - c) If any “dedicated output” function is enabled on a pin, it will take precedence over any remappable “output” function.
  - d) If any “dedicated digital” (input or output) function is enabled on a pin, any number of “input” remappable functions can be mapped to the same pin.
  - e) If any “dedicated analog” function(s) are enabled on a given pin, “digital input(s)” of any kind will all be disabled, although a single “digital output”, at the user’s cautionary discretion, can be enabled and active as long as there is no signal contention with an external analog input signal. For example, it is possible for the ADC to convert the digital output logic level, or to toggle a digital output on a comparator or ADC input provided there is no external analog input, such as for a built-in self-test.
  - f) Any number of “input” remappable functions can be mapped to the same pin(s) at the same time, including to any pin with a single output from either a dedicated or remappable “output”.

FIGURE 13-3: TYPE B/TIME C TIMER PAIR BLOCK DIAGRAM (32-BIT TIMER)



## 13.1 Timerx/y Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

**Note:** In the event you are not able to access the product page using the link above, enter this URL in your browser:  
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464>

### 13.1.1 KEY RESOURCES

- “Timers” (DS70362) in the “dsPIC33/PIC24 Family Reference Manual”
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related “dsPIC33/PIC24 Family Reference Manual” Sections
- Development Tools

**REGISTER 17-13: QE11LECH: QE11 LESS THAN OR EQUAL COMPARE HIGH WORD REGISTER**

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEILEC<31:24>							
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEILEC<23:16>							
bit 7				bit 0			

**Legend:**

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-0      **QEILEC<31:16>**: High Word Used to Form 32-Bit Less Than or Equal Compare Register (QE11LEC) bits

**REGISTER 17-14: QE11LECL: QE11 LESS THAN OR EQUAL COMPARE LOW WORD REGISTER**

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEILEC<15:8>							
bit 15				bit 8			

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEILEC<7:0>							
bit 7				bit 0			

**Legend:**

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-0      **QEILEC<15:0>**: Low Word Used to Form 32-Bit Less Than or Equal Compare Register (QE11LEC) bits

**REGISTER 21-6: CxINTF: ECANx INTERRUPT FLAG REGISTER (CONTINUED)**

bit 1      **RBIF:** RX Buffer Interrupt Flag bit  
            1 = Interrupt request has occurred  
            0 = Interrupt request has not occurred

bit 0      **TBIF:** TX Buffer Interrupt Flag bit  
            1 = Interrupt request has occurred  
            0 = Interrupt request has not occurred

**REGISTER 21-7: CxINTE: ECANx INTERRUPT ENABLE REGISTER**

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
IVRIE	WAKIE	ERRIE	—	FIFOIE	RBOVIE	RBIE	TBIE
bit 7							bit 0

**Legend:**

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 15-8      **Unimplemented:** Read as '0'
- bit 7      **IVRIE:** Invalid Message Interrupt Enable bit  
             1 = Interrupt request is enabled  
             0 = Interrupt request is not enabled
- bit 6      **WAKIE:** Bus Wake-up Activity Interrupt Enable bit  
             1 = Interrupt request is enabled  
             0 = Interrupt request is not enabled
- bit 5      **ERRIE:** Error Interrupt Enable bit  
             1 = Interrupt request is enabled  
             0 = Interrupt request is not enabled
- bit 4      **Unimplemented:** Read as '0'
- bit 3      **FIFOIE:** FIFO Almost Full Interrupt Enable bit  
             1 = Interrupt request is enabled  
             0 = Interrupt request is not enabled
- bit 2      **RBOVIE:** RX Buffer Overflow Interrupt Enable bit  
             1 = Interrupt request is enabled  
             0 = Interrupt request is not enabled
- bit 1      **RBIE:** RX Buffer Interrupt Enable bit  
             1 = Interrupt request is enabled  
             0 = Interrupt request is not enabled
- bit 0      **TBIE:** TX Buffer Interrupt Enable bit  
             1 = Interrupt request is enabled  
             0 = Interrupt request is not enabled

**BUFFER 21-3: ECAN™ MESSAGE BUFFER WORD 2**

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID5	EID4	EID3	EID2	EID1	EID0	RTR	RB1
bit 15							bit 8

U-x	U-x	U-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	RB0	DLC3	DLC2	DLC1	DLC0
bit 7							bit 0

**Legend:**

R = Readable bit      W = Writable bit      U = Unimplemented bit, read as '0'  
 -n = Value at POR      '1' = Bit is set      '0' = Bit is cleared      x = Bit is unknown

- bit 15-10      **EID<5:0>**: Extended Identifier bits
- bit 9      **RTR**: Remote Transmission Request bit  
 When IDE = 1:  
 1 = Message will request remote transmission  
 0 = Normal message  
 When IDE = 0:  
 The RTR bit is ignored.
- bit 8      **RB1**: Reserved Bit 1  
 User must set this bit to '0' per CAN protocol.
- bit 7-5      **Unimplemented**: Read as '0'
- bit 4      **RB0**: Reserved Bit 0  
 User must set this bit to '0' per CAN protocol.
- bit 3-0      **DLC<3:0>**: Data Length Code bits

**BUFFER 21-4: ECAN™ MESSAGE BUFFER WORD 3**

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 1							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 0							
bit 7							bit 0

**Legend:**

R = Readable bit      W = Writable bit      U = Unimplemented bit, read as '0'  
 -n = Value at POR      '1' = Bit is set      '0' = Bit is cleared      x = Bit is unknown

- bit 15-8      **Byte 1<15:8>**: ECAN Message Byte 1 bits
- bit 7-0      **Byte 0<7:0>**: ECAN Message Byte 0 bits

## 27.2 User ID Words

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices contain four User ID Words, located at addresses, 0x800FF8 through 0x800FFE. The User ID Words can be used for storing product information such as serial numbers, system manufacturing dates, manufacturing lot numbers and other application-specific information.

The User ID Words register map is shown in Table 27-3.

**TABLE 27-3: USER ID WORDS REGISTER MAP**

File Name	Address	Bits 23-16	Bits 15-0
FUID0	0x800FF8	—	UID0
FUID1	0x800FFA	—	UID1
FUID2	0x800FFC	—	UID2
FUID3	0x800FFE	—	UID3

**Legend:** — = unimplemented, read as '1'.

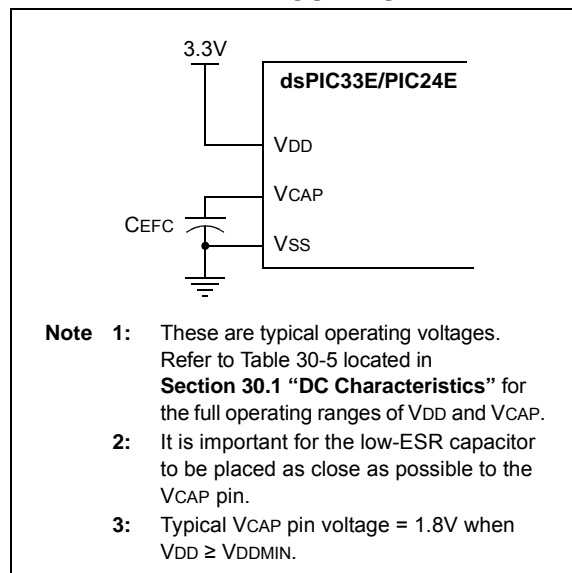
## 27.3 On-Chip Voltage Regulator

All of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices power their core digital logic at a nominal 1.8V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. A low-ESR (less than 1 Ohm) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 27-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 30-5 located in Section 30.0 "Electrical Characteristics".

**Note:** It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

**FIGURE 27-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR<sup>(1,2,3)</sup>**



## 27.4 Brown-out Reset (BOR)

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM is applied. The total delay in this case is TFSCM. Refer to Parameter SY35 in Table 30-22 of Section 30.0 "Electrical Characteristics" for specific TFSCM values.

The BOR status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.



TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles <sup>(2)</sup>	Status Flags Affected
46	MOV	MOV <i>f</i> , <i>Wn</i>	Move <i>f</i> to <i>Wn</i>	1	1	None
		MOV <i>f</i>	Move <i>f</i> to <i>f</i>	1	1	None
		MOV <i>f</i> , WREG	Move <i>f</i> to WREG	1	1	None
		MOV #lit16, <i>Wn</i>	Move 16-bit literal to <i>Wn</i>	1	1	None
		MOV.b #lit8, <i>Wn</i>	Move 8-bit literal to <i>Wn</i>	1	1	None
		MOV <i>Wn</i> , <i>f</i>	Move <i>Wn</i> to <i>f</i>	1	1	None
		MOV <i>Wso</i> , <i>Wdo</i>	Move <i>Ws</i> to <i>Wd</i>	1	1	None
		MOV WREG, <i>f</i>	Move WREG to <i>f</i>	1	1	None
		MOV.D <i>Wns</i> , <i>Wd</i>	Move Double from <i>W(ns):W(ns + 1)</i> to <i>Wd</i>	1	2	None
		MOV.D <i>Ws</i> , <i>Wnd</i>	Move Double from <i>Ws</i> to <i>W(nd + 1):W(nd)</i>	1	2	None
47	MOVPG	MOVPG #lit10, DSRPAG	Move 10-bit literal to DSRPAG	1	1	None
		MOVPG #lit9, DSWPAG	Move 9-bit literal to DSWPAG	1	1	None
		MOVPG #lit8, TBLPAG	Move 8-bit literal to TBLPAG	1	1	None
		MOVPG <i>Ws</i> , DSRPAG	Move <i>Ws</i> <9:0> to DSRPAG	1	1	None
		MOVPG <i>Ws</i> , DSWPAG	Move <i>Ws</i> <8:0> to DSWPAG	1	1	None
		MOVPG <i>Ws</i> , TBLPAG	Move <i>Ws</i> <7:0> to TBLPAG	1	1	None
48	MOVSAC	MOVSAC <i>Acc</i> , <i>Wx</i> , <i>Wxd</i> , <i>Wy</i> , <i>Wyd</i> , AWB <sup>(1)</sup>	Prefetch and store accumulator	1	1	None
49	MPY	MPY <i>Wm</i> * <i>Wn</i> , <i>Acc</i> , <i>Wx</i> , <i>Wxd</i> , <i>Wy</i> , <i>Wyd</i> <sup>(1)</sup>	Multiply <i>Wm</i> by <i>Wn</i> to Accumulator	1	1	OA,OB,OAB,SA,SB,SAB
		MPY <i>Wm</i> * <i>Wm</i> , <i>Acc</i> , <i>Wx</i> , <i>Wxd</i> , <i>Wy</i> , <i>Wyd</i> <sup>(1)</sup>	Square <i>Wm</i> to Accumulator	1	1	OA,OB,OAB,SA,SB,SAB
50	MPY.N	MPY.N <i>Wm</i> * <i>Wn</i> , <i>Acc</i> , <i>Wx</i> , <i>Wxd</i> , <i>Wy</i> , <i>Wyd</i> <sup>(1)</sup>	-(Multiply <i>Wm</i> by <i>Wn</i> ) to Accumulator	1	1	None
51	MSC	MSC <i>Wm</i> * <i>Wm</i> , <i>Acc</i> , <i>Wx</i> , <i>Wxd</i> , <i>Wy</i> , <i>Wyd</i> , AWB <sup>(1)</sup>	Multiply and Subtract from Accumulator	1	1	OA,OB,OAB,SA,SB,SAB

**Note 1:** These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

**2:** Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DI50	I <sub>IL</sub>	<b>Input Leakage Current<sup>(1,2)</sup></b> I/O Pins 5V Tolerant <sup>(3)</sup>	-1	—	+1	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub> , Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant <sup>(3)</sup>	-1	—	+1	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub> , Pin at high-impedance, $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$
DI51a		I/O Pins Not 5V Tolerant <sup>(3)</sup>	-1	—	+1	μA	Analog pins shared with external reference pins, $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$
DI51b		I/O Pins Not 5V Tolerant <sup>(3)</sup>	-1	—	+1	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub> , Pin at high-impedance, $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$
DI51c		I/O Pins Not 5V Tolerant <sup>(3)</sup>	-1	—	+1	μA	Analog pins shared with external reference pins, $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$
DI55		MCLR	-5	—	+5	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub>
DI56		OSC1	-5	—	+5	μA	V <sub>SS</sub> ≤ V <sub>PIN</sub> ≤ V <sub>DD</sub> , XT and HS modes

- Note 1:** The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.
- 2:** Negative current is defined as current sourced by the pin.
- 3:** See the “Pin Diagrams” section for the 5V tolerant I/O pins.
- 4:** V<sub>IL</sub> source < (V<sub>SS</sub> – 0.3). Characterized but not tested.
- 5:** Non-5V tolerant pins V<sub>IH</sub> source > (V<sub>DD</sub> + 0.3), 5V tolerant pins V<sub>IH</sub> source > 5.5V. Characterized but not tested.
- 6:** Digital 5V tolerant pins cannot tolerate any “positive” input injection current from input sources > 5.5V.
- 7:** Non-zero injection currents can affect the ADC results by approximately 4-6 counts.
- 8:** Any number and/or combination of I/O pins not excluded under I<sub>ICL</sub> or I<sub>ICH</sub> conditions are permitted provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 30-49: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended			
Param No.	Symbol	Characteristic <sup>(4)</sup>		Min. <sup>(1)</sup>	Max.	Units	Conditions
IM10	TLO:SCL	Clock Low Time	100 kHz mode	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
			400 kHz mode	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
			1 MHz mode <sup>(2)</sup>	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
IM11	THI:SCL	Clock High Time	100 kHz mode	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
			400 kHz mode	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
			1 MHz mode <sup>(2)</sup>	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	Cb is specified to be from 10 to 400 pF
			400 kHz mode	$20 + 0.1 C_b$	300	ns	
			1 MHz mode <sup>(2)</sup>	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	Cb is specified to be from 10 to 400 pF
			400 kHz mode	$20 + 0.1 C_b$	300	ns	
			1 MHz mode <sup>(2)</sup>	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode <sup>(2)</sup>	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	$\mu\text{s}$	
			400 kHz mode	0	0.9	$\mu\text{s}$	
			1 MHz mode <sup>(2)</sup>	0.2	—	$\mu\text{s}$	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	Only relevant for Repeated Start condition
			400 kHz mode	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
			1 MHz mode <sup>(2)</sup>	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	After this period, the first clock pulse is generated
			400 kHz mode	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
			1 MHz mode <sup>(2)</sup>	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
			400 kHz mode	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
			1 MHz mode <sup>(2)</sup>	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
			400 kHz mode	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
			1 MHz mode <sup>(2)</sup>	$T_{CY}/2$ (BRG + 2)	—	$\mu\text{s}$	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode <sup>(2)</sup>	—	400	ns	
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	$\mu\text{s}$	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	$\mu\text{s}$	
			1 MHz mode <sup>(2)</sup>	0.5	—	$\mu\text{s}$	
IM50	CB	Bus Capacitive Loading		—	400	pF	
IM51	TPGD	Pulse Gobbler Delay		65	390	ns	(Note 3)

**Note 1:** BRG is the value of the I<sup>2</sup>C™ Baud Rate Generator. Refer to “Inter-Integrated Circuit (I<sup>2</sup>C™)” (DS70330) in the “dsPIC33/PIC24 Family Reference Manual”. Please see the Microchip web site for the latest family reference manual sections.

**2:** Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

**3:** Typical value for this parameter is 130 ns.

**4:** These parameters are characterized, but not tested in manufacturing.

**Revision E (April 2012)**

This revision includes typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in Table A-3.

**TABLE A-4: MAJOR SECTION UPDATES**

Section Name	Update Description
<b>“16-bit Microcontrollers and Digital Signal Controllers (up to 512-Kbyte Flash and 48-Kbyte SRAM) with High-Speed PWM, Op amps, and Advanced Analog”</b>	<p>The following 512-Kbyte devices were added to the General Purpose Families table (see Table 1):</p> <ul style="list-style-type: none"> <li>• PIC24EP512GP202</li> <li>• PIC24EP512GP204</li> <li>• PIC24EP512GP206</li> <li>• dsPIC33EP512GP502</li> <li>• dsPIC33EP512GP504</li> <li>• dsPIC33EP512GP506</li> </ul> <p>The following 512-Kbyte devices were added to the Motor Control Families table (see Table 2):</p> <ul style="list-style-type: none"> <li>• PIC24EP512MC202</li> <li>• PIC24EP512MC204</li> <li>• PIC24EP512MC206</li> <li>• dsPIC33EP512MC202</li> <li>• dsPIC33EP512MC204</li> <li>• dsPIC33EP512MC206</li> <li>• dsPIC33EP512MC502</li> <li>• dsPIC33EP512MC504</li> <li>• dsPIC33EP512MC506</li> </ul> <p>Certain Pin Diagrams were updated to include the new 512-Kbyte devices.</p>
<b>Section 4.0 “Memory Organization”</b>	<p>Added a Program Memory Map for the new 512-Kbyte devices (see Figure 4-4).</p> <p>Added a Data Memory Map for the new dsPIC 512-Kbyte devices (see Figure 4-11).</p> <p>Added a Data Memory Map for the new PIC24 512-Kbyte devices (see Figure 4-16).</p>
<b>Section 7.0 “Interrupt Controller”</b>	Updated the VECNUM bits in the INTTREG register (see Register 7-7).
<b>Section 11.0 “I/O Ports”</b>	Added tip 6 to <b>Section 11.5 “I/O Helpful Tips”</b> .
<b>Section 27.0 “Special Features”</b>	<p>The following modifications were made to the Configuration Byte Register Map (see Table 27-1):</p> <ul style="list-style-type: none"> <li>• Added the column Device Memory Size (Kbytes)</li> <li>• Removed Notes 1 through 4</li> <li>• Added addresses for the new 512-Kbyte devices</li> </ul>
<b>Section 30.0 “Electrical Characteristics”</b>	<p>Updated the Minimum value for Parameter DC10 (see Table 30-4).</p> <p>Added Power-Down Current (I<sub>pd</sub>) parameters for the new 512-Kbyte devices (see Table 30-8).</p> <p>Updated the Minimum value for Parameter CM34 (see Table 30-53).</p> <p>Updated the Minimum and Maximum values and the Conditions for parameter SY12 (see Table 30-22).</p>

**Revision H (August 2013)**

This revision includes minor typographical and formatting changes throughout the text.

Other major changes are referenced by their respective section in Table A-6.

**TABLE A-6: MAJOR SECTION UPDATES**

Section Name	Update Description
<b>Cover Section</b>	<ul style="list-style-type: none"> <li>• Adds Peripheral Pin Select (PPS) to allow Digital Function Remapping and Change Notification Interrupts to Input/Output section</li> <li>• Adds heading information to 64-Pin TQFP</li> </ul>
<b>Section 4.0 “Memory Organization”</b>	<ul style="list-style-type: none"> <li>• Corrects Reset values for ANSELE, TRISF, TRISC, ANSELC and TRISA</li> <li>• Corrects address range from 0x2FFF to 0x7FFF</li> <li>• Corrects DSRPAG and DSWPAG (now 3 hex digits)</li> <li>• Changes Call Stack Frame from &lt;15:1&gt; to PC&lt;15:0&gt;</li> <li>• Word length in Figure 4-20 is changed to 50 words for clarity</li> </ul>
<b>Section 5.0 “Flash Program Memory”</b>	<ul style="list-style-type: none"> <li>• Corrects descriptions of NVM registers</li> </ul>
<b>Section 9.0 “Oscillator Configuration”</b>	<ul style="list-style-type: none"> <li>• Removes resistor from Figure 9-1</li> <li>• Adds Fast RC Oscillator with Divide-by-16 (FRCDIV16) row to Table 9-1</li> <li>• Removes incorrect information from ROI bit in Register 9-2</li> </ul>
<b>Section 14.0 “Input Capture”</b>	<ul style="list-style-type: none"> <li>• Changes 31 user-selectable Trigger/Sync interrupts to 19 user-selectable Trigger/Sync interrupts</li> <li>• Corrects ICTSEL&lt;12:10&gt; bits (now ICTSEL&lt;2:0&gt;)</li> </ul>
<b>Section 17.0 “Quadrature Encoder Interface (QEI) Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)”</b>	<ul style="list-style-type: none"> <li>• Corrects QCAPEN bit description</li> </ul>
<b>Section 19.0 “Inter-Integrated Circuit™ (I<sup>2</sup>C™)”</b>	<ul style="list-style-type: none"> <li>• Adds note to clarify that 100kbit/sec operation of I<sup>2</sup>C is not possible at high processor speeds</li> </ul>
<b>Section 22.0 “Charge Time Measurement Unit (CTMU)”</b>	<ul style="list-style-type: none"> <li>• Clarifies Figure 22-1 to accurately reflect peripheral behavior</li> </ul>
<b>Section 23.0 “10-Bit/12-Bit Analog-to-Digital Converter (ADC)”</b>	<ul style="list-style-type: none"> <li>• Correct Figure 23-1 (changes CH123x to CH123Sx)</li> </ul>
<b>Section 24.0 “Peripheral Trigger Generator (PTG) Module”</b>	<ul style="list-style-type: none"> <li>• Adds footnote to Register 24-1 (In order to operate with CVRSS=1, at least one of the comparator modules must be enabled).</li> </ul>
<b>Section 25.0 “Op Amp/Comparator Module”</b>	<ul style="list-style-type: none"> <li>• Adds note to Figure 25-3 (In order to operate with CVRSS=1, at least one of the comparator modules must be enabled)</li> <li>• Adds footnote to Register 25-2 (COE is not available when OPMODE (CMxCON&lt;10&gt;) = 1)</li> </ul>
<b>Section 27.0 “Special Features”</b>	<ul style="list-style-type: none"> <li>• Corrects the bit description for FNOSC&lt;2:0&gt;</li> </ul>
<b>Section 30.0 “Electrical Characteristics”</b>	<ul style="list-style-type: none"> <li>• Corrects 512K part power-down currents based on test data</li> <li>• Corrects WDT timing limits based on LPRC oscillator tolerance</li> </ul>
<b>Section 31.0 “High-Temperature Electrical Characteristics”</b>	<ul style="list-style-type: none"> <li>• Adds Table 31-5 (DC Characteristics: Idle Current (I<sub>IDLE</sub>))</li> </ul>